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Honorable Commissioner for Patents  
P.O. Box 1450,  
Alexandria, VA 22313

Atty.Docket No.: **P69337US0**  
**CUSTOMER NUMBER: 00136**

Sir:

Transmitted herewith for filing is the patent application in the name of:

**Joon Hyeon LEE of Cheongjoo-Shi, Republic of Korea,**

for **METHOD OF FORMING METAL LINE LAYER IN SEMICONDUCTOR DEVICE**. The application comprises a 13-page specification including 11 claims (1 independent) and Abstract, 3 sheets of drawings (Figs. 1A-4), and a Declaration and Power of Attorney.

Also accompanying this application for filing is:

- (1) Assignment document, cover sheet and **\$40.00** fee for recordation of Assignment;
- (2) Information Disclosure Statement, Form PTO-1449 and copies of references; and
- (3) A certified copy of **Korean** Application No. **2003-49249**, filed **July 18, 2003**, the priority of which is claimed under 35 U.S.C. §119.

The filing fee has been calculated as shown:

Large Entity		\$ 770.00
Total Claims= <u>11</u> ;	in excess of 20 = 0 x (\$18.00) =	
Total Ind. Claims= <u>1</u> ;	in excess of 03 = 0 x (\$86.00) =	+
TOTAL FILING FEE:		<b>\$ 770.00</b>

A Credit Card Payment Form authorizing the amount of **\$810.00** is enclosed to cover the Filing Fee and an Assignment Recordation Fee. The Commissioner is hereby authorized to charge payment of any fees set forth in §§1.16 or 1.17 during the pendency of this application, or credit any overpayment, to Deposit Account No. 06-1358. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

By: 

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YSH:kyc  
Enclosures